imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







P-Channel Enhancement-Mode Vertical DMOS FET

Features

- Low threshold
- High input impedance
- Low input capacitance
- Fast switching speeds
- Free from secondary breakdown
- Low input and output leakage

Applications

- Logic level interfaces
- Solid state relays
- Linear amplifiers
- Power management
- Analog switches
- Telecom switches

Ordering Information

Part Number	Package Option	Packing		
TP2435N8-G	TO-243AA (SOT-89)	2000/Reel		

-G denotes a lead (Pb)-free / RoHS compliant package.

Contact factory for Wafer / Die availablity.

Devices in Wafer / Die form are lead (Pb)-free / RoHS compliant.

Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV _{DSS}
Drain-to-gate voltage	BV _{DGS}
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Typical Thermal Resistance

Package	$\boldsymbol{\theta}_{_{ja}}$
TO-243AA (SOT-89)	133°C/W

General Description

This low threshold enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

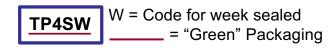
Product Summary

$\mathbf{BV}_{\mathrm{DSS}}/\mathbf{BV}_{\mathrm{DGS}}$	R _{DS(ON)}	V _{GS(th)}	l _{D(ON)}		
	(max)	(max)	(min)		
-350V	15Ω	-2.4V	-800mA		

Pin Configuration



Product Marking



Package may or may not include the following marks: Si or 🎲

TO-243AA (SOT-89)

TP2435

Thermal Characteristics

Package	Ι _D (continuous) [†]	Ι _D (pulsed)	Power Dissipation @ T _A = 25°C		I _{DRM}	
TO-243AA (SOT-89)	-231mA	-1.1A	1.6W	-231mA	-1.1A	

 $\begin{array}{c} \uparrow & I_{_{D}} \mbox{ (continuous) is limited by max rated } T_{_{j}} \mbox{.} \\ \ddagger & Mounted on FR5 board, 25mm x 25mm x 1.57mm. \end{array}$

Electrical Characteristics ($T_A = 25^{\circ}C$ unless otherwise specified)

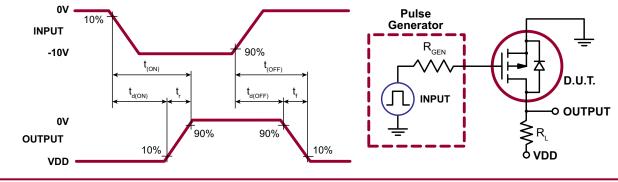
Sym	Parameter	Min	Тур	Max	Units	Conditions		
BV _{DSS}	Drain-to-source breakdown voltage	-350	-	-	V	V _{GS} = 0V, I _D = -250µA		
V _{GS(th)}	Gate threshold voltage	-1.0	-	-2.4	V	$V_{GS} = V_{DS}, I_{D} = -1.0 \text{mA}$		
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	4.5	mV/ºC	$V_{GS} = V_{DS}, I_{D} = -1.0 \text{mA}$		
I _{GSS}	Gate body leakage	-	-	-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$		
			-	-10	μA	V_{GS} = 0V, V_{DS} = Max Rating		
I _{DSS}	Zero gate voltage drain current	-	-	-1.0	mA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$, $T_A = 125^{\circ}C$		
	On-state drain current	-0.3	-	-	A	V _{GS} = -4.5V, V _{DS} = -25V		
I _{D(ON)}		-0.8	-	-		V _{GS} = -10V, V _{DS} = -25V		
	Static drain-to-source on-state resistance	-	-	15	Ω	V_{GS} = -3.0V, I _D = -20mA		
R _{DS(ON)}		-	-	15		V _{GS} = -4.5V, I _D = -150mA		
		-	-	15		V _{GS} = -10V, I _D = -500mA		
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	1.7	%/°C	V _{GS} = -10V, I _D = -150mA		
G _{FS}	Forward transconductance	125	-	-	mmho	V _{DS} = -25V, I _D = -350mA		
C _{ISS}	Input capacitance	-	-	200		V _{GS} = 0V,		
C _{oss}	Common source output capacitance	-	-	70	pF	$V_{DS} = -25V,$		
C _{RSS}	Reverse transfer capacitance	-	-	25		f = 1.0 MHz		
t _{d(ON)}	Turn-on delay time	-	-	15				
t,	Rise time	-	-	20	1	$V_{DD} = -25V,$ $I_{D} = -250mA,$ $R_{GEN} = 25\Omega$		
t _{d(OFF)}	Turn-off delay time	-	-	25	ns			
t _r	Fall time	-	-	50				
V _{SD}	Diode forward voltage drop	-	-	-1.5	V	V _{GS} = 0V, I _{SD} = -750mA		
t _{rr}	Reverse recovery time	-	300	-	ns	V _{GS} = 0V, I _{SD} = -750mA		

Notes:

All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.) 1.

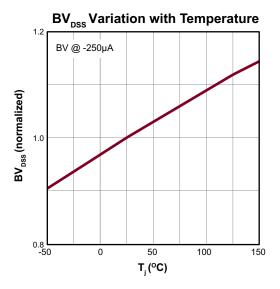
2. All A.C. parameters sample tested.

Switching Waveforms and Test Circuit

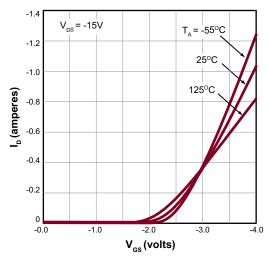


TP2435

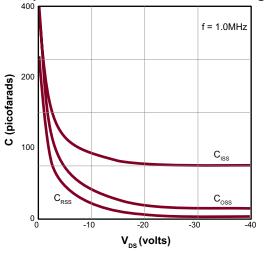
Typical Performance Curves

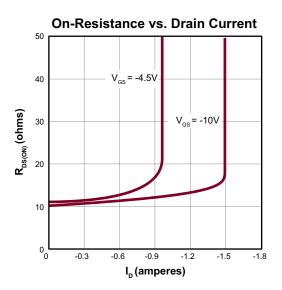


Transfer Characteristics

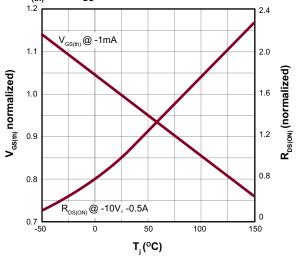


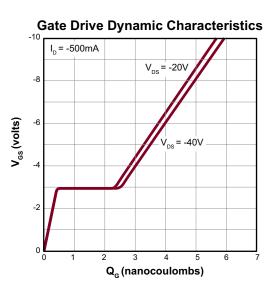
Capacitance vs. Drain-to-Source Voltage





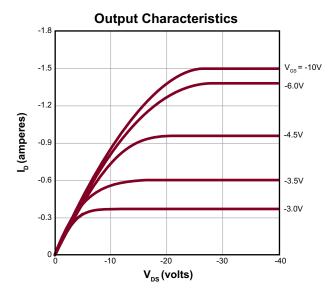
 $\mathbf{V}_{\text{(th)}} \text{ and } \mathbf{R}_{\text{DS}} \text{ Variation with Temperature}$

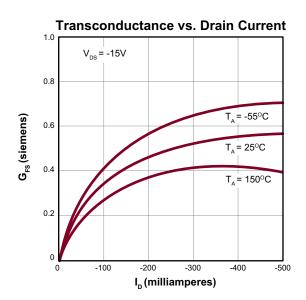




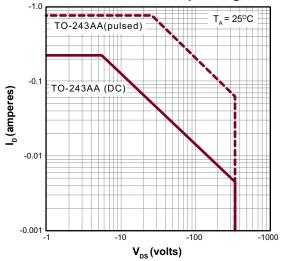
TP2435

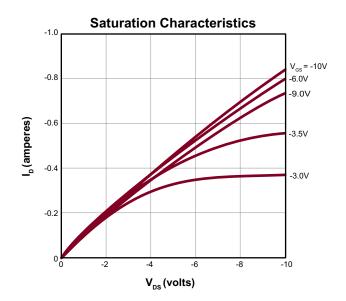
Typical Performance Curves (cont.)



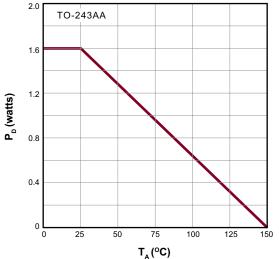


Maximum Rated Safe Operating Area



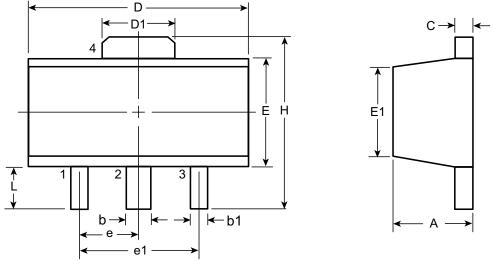


Power Dissipation vs. Ambient Temperature



Thermal Response Characteristics 1.0 Thermal Resistance (normalized) 0.8 0.6 TO-243AA $T_{A} = 25^{\circ}C$ $P_{D} = 1.6W$ 0.4 0.2 0 0.001 0.01 0.01 1.0 10 t_p (seconds)

3-Lead TO-243AA (SOT-89) Package Outline (N8)



Top View

Side View

Symbo	ol	Α	b	b1	С	D	D1	E	E1	е	e1	Н	L
Dimensions (mm)	MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00†		3.00 BSC	3.94	0.73*
	NOM	-	-	-	-	-	-	-	-			-	-
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29		200	4.25	1.20

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.

† This dimension differs from the JEDEC drawing

Drawings not to scale.

Supertex Doc. #: DSPD-3TO243AAN8, Version F111010.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <u>http://www.supertex.com/packaging.html</u>.)

Supertex inc. does not recommend the use of its products in life support applications, and will not knowingly sell them for use in such applications unless it receives an adequate "product liability indemnification insurance agreement." **Supertex inc.** does not assume responsibility for use of devices described, and limits its liability to the replacement of the devices determined defective due to workmanship. No responsibility is assumed for possible omissions and inaccuracies. Circuitry and specifications are subject to change without notice. For the latest product specifications refer to the **Supertex inc.** (website: http://www.supertex.com)

©2013 Supertex inc. All rights reserved. Unauthorized use or reproduction is prohibited.